

PMP4499 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C2, C18	2	1000pF	GRM1885C1H102FA01J	MuRata	CAP, CERM, 1000 pF, 50 V, +/- 1%, C0G, 0603	0603
C3, C5, C7, C16,	4	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603
C4	1	0.022uF	C2012C0G1E223J	TDK	CAP, CERM, 0.022 μ F, 25 V, +/- 5%, C0G/NP0, 0805	0805_HV
C6	1	4.7uF	GRM21BR71A475KA73L	MuRata	CAP, CERM, 4.7 μ F, 10 V, +/- 10%, X7R, 0805	0805_HV
C8	1	0.1uF	C0603C104J3RACTU	Kemet	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	0603
C25	1	0.022uF	GRM188R71H223KA01D	MuRata	CAP, CERM, 0.022 μ F, 50 V, +/- 10%, X7R, 0603	0603
C39	1	1800pF	GRM188R71H182KA01D	MuRata	CAP, CERM, 1800 pF, 50 V, +/- 10%, X7R, 0603	0603
C11, C17, C19, C38	4	1000pF	GRM1885C1E102JA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0603	0603
C12, C13, C14, C15, C23, C24	6	10uF	GRM31CR71E106KA12L	MuRata	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	1206
C20	1	330pF	GRM1885C1H331JA01D	MuRata	CAP, CERM, 330 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C27	1	680uF	6TPE680ML	Panasonic	680 μ F, 6.3 V, +/- 20%, 0.025 ohm, 7.3x2.8x4.3mm SMD, CAP, Tantalum Polymer	CAPSMT_6_D3L
C22 C21	0	68uF	APXE160ARA680MF61G	Panasonic	CAP, AL, 68 μ F, 16 V, +/- 20%, 0.028 ohm, SMD	CAPSMT_6_D3L
C28, C29, C30, C41, C43, C44	6	47uF	GRM31CR61A476KE15L	MuRata	CAP, CERM, 47 μ F, 10 V, +/- 10%, X5R, 1206	1206
J1	1		5103308-1	TE Connectivity	Header (shrouded), 100mil, 5x2, Gold, TH	CONN_5103308-1
J2	1		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS	CONN_ED120-2DS
L1	1	300nH	SLC1480-301MLB	Coilcraft	Inductor, Shielded, Ferrite, 300 nH, 52 A, 0.00015 ohm, SMD	SLC1480
Q1	1	0.2V	MMBT3904	Fairchild Semiconductor	Transistor, NPN, 40V, 0.2A, SOT-23	SOT-23
R1	1	100k	RC0603FR-07100KL	Yageo America	RES, 100 k, 1%, 0.1 W, 0603	0603
R2, R21, R18	3	10.0k	RC0603FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R3, R10, R14, R13 R15, R22	6	0	RC0603JR-070RL	Yageo America	RES, 0, 5%, 0.1 W, 0603	0603
R19 R20	2	51	RC0603FR-0751RL	Yageo America	RES, 51.0, 1%, 0.1 W, 0603	0603
R4	1	2.00k	RC0603FR-072KL	Yageo America	RES, 2.00 k, 1%, 0.1 W, 0603	0603
R6	1	10.0k	RC0603FR-0720KL	Yageo America	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R8, R11, R12	3	39.0k	RC0603FR-0739KL	Yageo America	RES, 39.0 k, 1%, 0.1 W, 0603	0603
R9	1	62.0k	RC0603FR-0762KL	Yageo America	RES, 62.0 k, 1%, 0.1 W, 0603	0603
R16	1	1	CRCW12061R00JNEA	Vishay-Dale	RES, 1.0 ohm, 5%, 0.25W, 1206	1206
T1, T2	2	50A	CB35-36-CY	Panduit	Terminal 50A Lug	CB35-36-CY
TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9	9	Red	5000	Keystone	Test Point, Miniature, Red, TH	Keystone5000
U1	1		TPS544C20RVF	Texas Instruments	TPS544C20 18V, 30A PMBUS SYNCHRONOUS BUCK CONVERTERS, RVF0040A	RVF0040A

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